

Hardware - UD3

- Actividad 1 -

Placas bases y características

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Placa base:

[Link Página Asus Placa TUF GAMINGB760-PLUS WIFI D4](https://www.asus.com/es/motherboards-components/motherboards/tuf-gaming/tuf-gaming-b760-plus-wifi-d4/)

<https://www.asus.com/es/motherboards-components/motherboards/tuf-gaming/tuf-gaming-b760-plus-wifi-d4/>

Manual Oficial Asus Usuario:

https://dlcdnets.asus.com/pub/ASUS/mb/LGA1700/TUF_GAMING_B760-PLUS_WIFI_D4/E21224_TUF_GAMING_B760-PLUS_WIFI_D4_UM_WEB.pdf?model=TUF%20GAMING%20B760-PLUS%20WIFI%20D4

Otros Manuales:

- [PRIME PROART TUF GAMING INTEL 700 Series BIOS Manual \(English Edition \)](#)
- [INTEL RAID Configuration Guide \(English Edition \)](#)



Características Técnicas:

Factor de forma (dimensiones)

ATX Form Factor 12 inch x 9.6 inch (30.5 cm x 24.4 cm)

Form Factor	ATX Form Factor 12 inch x 9.6 inch (30.5 cm x 24.4 cm)
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Socket CPU (dimensiones y pines)

Intel® Socket LGA1700 for 13th Gen Intel® Core™ & 12th Gen Intel® Core™, Pentium® Gold and Celeron® Processors*

Supports Intel® Turbo Boost Technology 2.0 and Intel® Turbo Boost Max Technology 3.0**

CPU	Intel® Socket LGA1700 for 13 th Gen Intel® Core™ & 12 th Gen Intel® Core™, Pentium® Gold and Celeron® Processors* Supports Intel® Turbo Boost Technology 2.0 and Intel® Turbo Boost Max Technology 3.0** * Refer to www.asus.com for CPU support list. ** Intel® Turbo Boost Max Technology 3.0 support depends on the CPU types.
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Bancos de memoria RAM (DIMM)

4 x DIMM, Max. 128GB, DDR4 Non-ECC, Un-buffered Memory* Dual Channel Memory Architecture

Memory	4 x DIMM, Max. 128GB, DDR4 Non-ECC, Un-buffered Memory* Dual Channel Memory Architecture Supports Intel® Extreme Memory Profile (XMP) OptiMem II * Supported memory types, data rate (speed), and number of DRAM modules vary depending on the CPU and memory configuration, for more information please refer to CPU/Memory Support under the Support tab or visit https://www.asus.com/support/ .
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Componentes Compatibles con la Placa Base del Sistema de Procesamiento:

Microprocesador:

Con GPU integrada:

Link: <https://www.pccomponentes.com/intel-core-i9-13900k-3-ghz-box>

Intel Core i9-13900K

Sin GPU integrada:

Link: https://www.pccomponentes.com/intel-core-i5-13400f-25-ghz-46-ghz?campaigntype=pmax&campaignname=pmaxOfertastop&gad_source=1&gclid=EAlaIQobChMIicfn4NncggMVhU5BAh1SOwx1EAQYAYABEgKJWvD_BwE

Intel Core i5-13400F 2.5 GHz/4.6 GHz

Disipador con Ventilador:

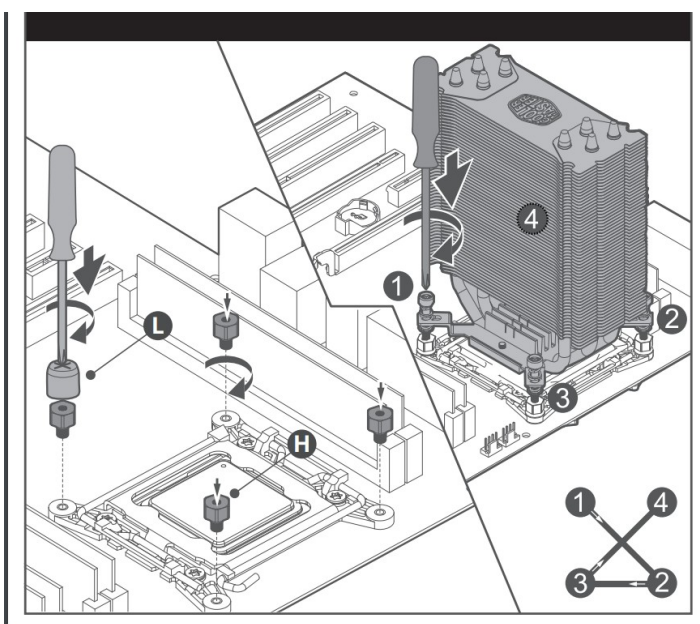
Link: https://www.pccomponentes.com/cooler-master-hyper-212-led-turbo-argb-ventilador-cpu?campaigntype=eshopping&campaignchannel=shopping&gad_source=1&gclid=EAlaIQobChMIjaHm4tzcggMV8IRoCR1rZQv1EAQYASABEgJCtfD_BwE

Cooler Master Hyper 212 LED Turbo ARGB Ventilador CPU

Manual link:

https://manuals.plus/m/826c7f6c282b0028977aff45be304d363bf164cfcd2d8108c22221b3bbe7d524_optim.pdf

Sistema de atornillado:



Pasta Térmica de Alto Grado de Transmitancia de Temperatura:

Link: <https://www.pccomponentes.com/forgeon-lichborne-pasta-termica-4g-135w-mk>

Forgeon Lichborne Pasta Térmica 4g 13.5W/mK

